



ThinFlex

ThinFlex Corporation

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ThinFlex-W22, W-2010RD-C Adhesiveless Double Sided Copper Clad Laminate (Halogen Free)

ThinFlex-W22, W-2010RD-C is an adhesiveless double-sided (D/S) copper clad laminate, using ThinFlex TPI film and laminated with RA copper foil on both sides. The W-2010RD-C adhesiveless D/S composites are designed for a wide variety of flexible circuit applications which require advanced material performance and high reliability.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Excellent etching capability
- * Excellent flame resistance
- * Excellent chemical resistance
- * Excellent thermal, mechanical, and electrical properties
- * Low moisture absorption

2. Specifications:

W- 20 10 R D-C

Product	Thickness of PI	Thickness of Cu	Cu Type	Structure	Cu Supplier
W-type FCCL	20 : 2.0 mil	10 : 1 Oz.	R : RA	D: D/S	Fukuda
Product Size	W: 250/500 ± 1mm; L: 400~700 ± 2mm (sheet type) W: 250/500 ± 1mm; L: 100 +2/-0m (roll type)				

* Other product size is also available on customer's demand.



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3. Construction:

Copper foil
Polyimide film

4. Properties:

Copper foil

Test item	Unit	W-2010RD-C	Test Method
Peel Strength			
As Received	Kgf/cm	≥ 0.6	JIS C 6471 Method B
Solder Float	Kgf/cm	≥ 0.6	JIS C 6471 Method B
After Temp. Cycling	Kgf/cm	≥ 0.6	JIS C 6471 Method B
Chemical Resistance	Kgf/cm	≥ 0.6	JIS C 6471 Method B
Tensile Strength (Base Film)	Kg/mm ²	≥ 25	IPC-TM-650 2.4.19
Elongation (Base Film)	%	≥ 25	IPC-TM-650 2.4.19
Tensile Modulus (Base Film)	Kg/mm ²	≥ 600	ASTM D882
Initial Tear Strength (Base Film)	g	≥ 1250	IPC-TM-650 2.4.16
Propagation Tear Strength (Base Film)	g	≥ 15	IPC-TM-650 2.4.17.1
Flexural Endurance, MIT			
M.D.	Cycles	≥ 50	JIS-C 6471, 0.8mmR, 0.5kg
T.D.	Cycles	≥ 50	JIS-C 6471, 0.8mmR, 0.5kg
Electrical Properties			
Surface Resistance	Ω	≥ 1.0×10 ¹¹	IPC-TM650 2.5.17
Volume Resistance	Ω-cm	≥ 1.0×10 ¹²	IPC-TM650 2.5.17
Insulation Resistance	Ω	≥ 1.0×10 ⁹	IPC-TM650 2.6.3.2
Dielectric Strength	kV/mil	5.5	ASTM-D149
Dielectric Constant	-	3.3	IPC-TM650 2.5.5.3
Dissipation factor	-	0.01	IPC-TM650 2.5.5.3
Physical and Thermal Properties			
Dimensional Stability	M.D.	%	-0.1~0.1
	T.D.	%	-0.1~0.1
CTE	ppm/°C	24	ThinFlex
T _g	°C	350	ThinFlex
Solder Float	30sec at 288°C (550°F)	-	Pass
Moisture Absorption	%	1.1	IPC-TM650 2.6.2
Chemical Resistance	-	Pass	IPC-TM650 2.3.2
Thickness tolerance	um	120±10%	ThinFlex
UL Flame Class	-	V-0	UL94

* Above data are typical values, and are not guaranteed values.



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5. Storage:

ThinFlex-W22, W-2010RD-C will meet its shelf-life for at least 12 months after arrival at purchaser's factory with original package, stored at temperature of 25°C or less and relative humidity of 70% or less. The product is no need to be kept in the refrigeration.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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